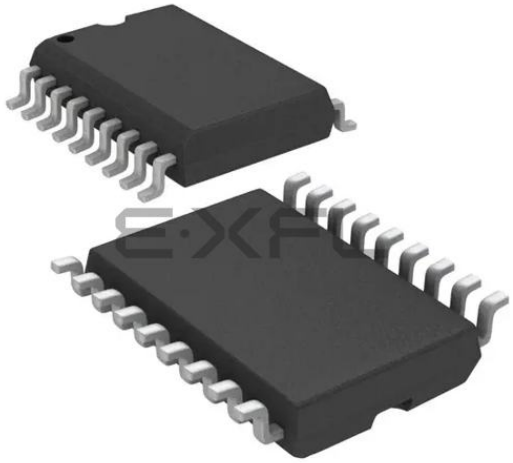

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	12
Program Memory Size	768B (512 x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	3.5V ~ 15V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16hv540-04i-so

2.0 PIC16HV540 DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in this section. When placing orders, please use the PIC16HV540 Product Identification System at the back of this data sheet to specify the correct part number.

For the PIC16HV540 family of devices, there is one device type, as indicated in the device number:

1. **HV**, as in PIC16HV540. These devices have EPROM program memory and operate over the standard voltage range of 3.5 to 15 volts.

2.1 UV Erasable Devices

The UV erasable versions, offered in CERDIP packages, are optimal for prototype development and pilot programs.

UV erasable devices can be programmed for any of the four oscillator configurations. Microchip's PICSTART® and PRO MATE® programmers both support programming of the PIC16HV540. Third party programmers also are available; refer to Literature Number DS00104 for a list of sources.

2.2 One-Time-Programmable (OTP) Devices

The availability of OTP devices is especially useful for customers expecting frequent code changes and updates.

The OTP devices, packaged in plastic packages, permit the user to program them once. In addition to the program memory, the configuration bits must be programmed.

2.3 Quick-Turnaround-Production (QTP) Devices

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who choose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices but with all EPROM locations and configuration bit options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. (Please contact your Microchip Technology sales office for more details.)

2.4 Serialized Quick-Turnaround-Production (SQTP) Devices

Microchip offers the unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential.

Serial programming allows each device to have a unique number which can serve as an entry code, password or ID number. (Please contact your Microchip Technology sales office for more details.)

TABLE 3-1: PINOUT DESCRIPTION - PIC16HV540

Name	DIP, SOIC No.	SSOP No.	I/O/P Type	Input Levels	Description	
RA0	17	19	I/O	TTL	Independently regulated Bi-directional I/O port — VIO	
RA1	18	20	I/O	TTL		
RA2	1	1	I/O	TTL		
RA3	2	2	I/O	TTL		
RB0	6	7	I/O	TTL	High-voltage Bi-directional I/O port. Sourced from VDD.	Wake-up on pin change
RB1	7	8	I/O	TTL		
RB2	8	9	I/O	TTL		
RB3	9	10	I/O	TTL		
RB4	10	11	I/O	TTL		
RB5	11	12	I/O	TTL		
RB6	12	13	I/O	TTL		
RB7	13	14	I/O	TTL		Wake-up on SLOW rising pin change.
T0CKI	3	3	I	ST	Clock input to Timer 0. Must be tied to VSS or VDD, if not in use, to reduce current consumption.	
$\overline{MCLR}$/VPP	4	4	I	ST	Master clear (reset) input/programming voltage input. This pin is an active low reset to the device. Voltage on the $\overline{MCLR}$/VPP pin must not exceed VDD(1) to avoid unintended entering of programming mode.	
OSC1/CLKIN	16	18	I	ST	Oscillator crystal input/external clock source input.	
OSC2/CLKOUT	15	17	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, OSC2/CLKOUT output is connected to TMR0, bit 0. Frequencies of CLKIN/8 to CLKIN/1024 can be generated on this pin.	
VDD	14	15,16	P	—	Positive supply.	
VSS	5	5,6	P	—	Ground reference.	

Legend: I = input, O = output, I/O = input/output, P = power, — = Not Used, TTL = TTL input, ST = Schmitt Trigger input.

Note 1: VDD during programming mode can not exceed parameter PD1 called out in the PIC16C5X Programming Specification (Literature number DS30190).

4.6 Program Counter

As a program instruction is executed, the Program Counter (PC) will contain the address of the next program instruction to be executed. The PC value is increased by one every instruction cycle, unless an instruction changes the PC.

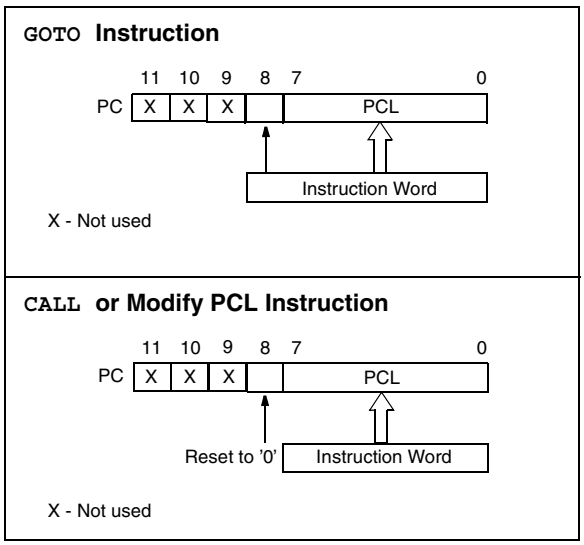
For a GOTO instruction, bits 8:0 of the PC are provided by the GOTO instruction word. (Figure 4-3).

For a CALL instruction, or any instruction where the PCL is the destination, bits 7:0 of the PC again are provided by the instruction word. However, PC<8> does not come from the instruction word, but is always cleared (Figure 4-3).

Instructions where the PCL is the destination, or Modify PCL instructions, include MOVWF PC, ADDWF PC, and BSF PC, 5. .

Note:	Because PC<8> is cleared in the CALL instruction, or any Modify PCL instruction, all subroutine calls or computed jumps are limited to the first 256 locations of any program memory page (512 words long).

FIGURE 4-3: LOADING OF PC BRANCH INSTRUCTIONS - PIC16HV540



4.6.1 EFFECTS OF RESET

The Program Counter is set upon a RESET, which means that the PC addresses the last location in the last page i.e., the reset vector.

The STATUS register page preselect bits are cleared upon a RESET, which means that page 0 is preselected.

Therefore, upon a RESET, a GOTO instruction at the reset vector location will automatically cause the program to jump to page 0.

4.7 Stack

PIC16HV540 device has a 12-bit wide L.I.F.O. (last in, first out) hardware 4 level stack.

A CALL instruction will *push* the current value of stack 1 into stack 2 and then push the current program counter value, incremented by one, into stack level 1. If more than four sequential CALL's are executed, only the most recent four return addresses are stored.

A RETLW instruction will *pop* the contents of stack level 1 into the program counter and then copy stack level 2 contents into level 1. If more than four sequential RETLW's are executed, the stack will be filled with the address previously stored in level 4. Note that the W register will be loaded with the literal value specified in the instruction. This is particularly useful for the implementation of data look-up tables within the program memory.

Upon any reset, the contents of the stack remain unchanged, however the program counter (PCL) will also be reset to 0.

Note 1:	There are no STATUS bits to indicate stack overflows or stack underflow conditions.
Note 2:	There are no instructions mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL and RETLW instructions.

NOTES:

5.0 I/O PORTS

As with any other register, the I/O registers can be written and read under program control. However, read instructions (e.g., `MOVF PORTB,W`) always read the I/O pins independent of the pin's input/output modes. On RESET, all I/O ports are defined as input (inputs are at hi-impedance) since the I/O control registers (TRISA, TRISB) are all set.

5.1 PORTA

PORTA is a 4-bit I/O register. Only the low order 4 bits are used (RA3:RA0). Bits 7-4 are unimplemented and read as '0's. The inputs will tolerate input voltages as high as V_{IO} and outputs will swing from V_{SS} to V_{IO}. The internal voltage regulator V_{IO} powers PORTA I/O pads. The internal regulator output, V_{IO}, is switchable between 3Vdc and 5Vdc, via the (RL) bit in the OPTION2 register.

5.2 PORTB

PORTB is an 8-bit I/O register (PORTB<7:0>). All 8 PORTB I/Os are high voltage I/O. The inputs will tolerate input voltages as high as V_{DD} and outputs will swing from V_{SS} to V_{DD}. In addition, 5 of the PORTB pins can be configured for the wake-up on change feature. Pins RB0, RB1, RB2 and RB3 latch the state of the pin at the onset of sleep mode. (No "dummy" read of the PORTB pins is required prior to executing the `SLEEP` instruction.) A level change on the input resets the device, implementing wake-up on pin change. The $\overline{\text{PCWUF}}$ bit in the status register is cleared to indicate that a pin change caused the reset. This feature can be enabled/disabled in the OPTION2 register.

PORTB pin RB7 also exhibits this wake-up on pin high feature but is specially adapted for a slow-rising input signal. This special feature prevents excessive power consumption when desiring long sleep periods without using the watchdog timer and prescaler. $\overline{\text{PCWUF}}$ bit in the status register is cleared to indicate that a pin change caused the reset. This feature can be enabled/disabled in the OPTION2 register.

Only pins configured as inputs can cause this wake-up on pin change to occur.

To prevent false wake-up on pin change events on pins RB<0:3>, the pin state must be driven to a logic 1 or logic 0 and not left floating during the "`SLEEP`" state. For pin RB7, the pin state must be driven to logic 0 and allowed to ramp to a logic 1 for correct operation.

5.3 TRIS Registers

The output driver control registers are loaded with the contents of the W register by executing the `TRIS f` instruction. A '1' from a TRIS register bit puts the corresponding output driver in a hi-impedance mode. A '0' puts the contents of the output data latch on the selected pins, enabling the output buffer.

Note:	A read of the ports reads the pins, not the output data latches. That is, if an output driver on a pin is enabled and driven high, but the external system is holding it low, a read of the port will indicate that the pin is low.

The TRIS registers are "write-only" and are set (output drivers disabled) upon RESET.

5.4 I/O Interfacing

The equivalent circuit for the PORTA and PORTB I/O pins are shown in Figure 5-1 through Figure 5-4. All ports may be used for both input and output operation. For input operations, these ports are non-latching. Any input must be present until read by an input instruction (e.g., `MOVF PORTB, W`). The outputs are latched and remain unchanged until the output latch is rewritten. To use a port pin as output, the corresponding direction control bit (in TRISA, TRISB) must be cleared (= 0). For use as an input, the corresponding TRIS bit must be set. Any I/O pin can be programmed individually as input or output.

6.1 Using Timer0 with an External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (TOSC) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

6.1.1 EXTERNAL CLOCK SYNCHRONIZATION

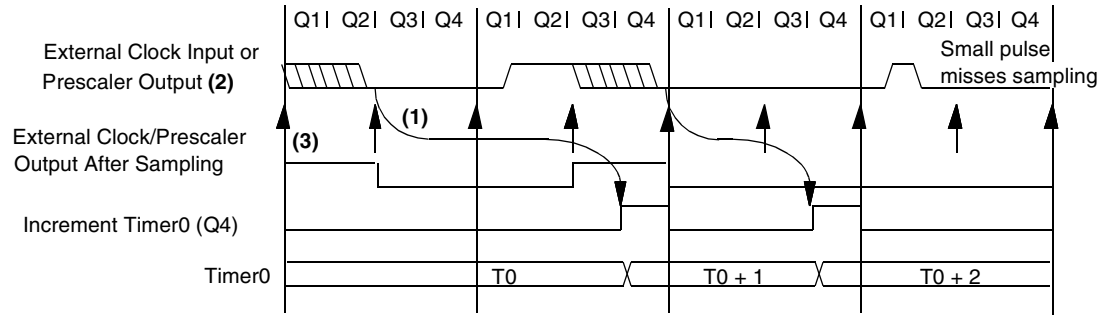
When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 6-5). Therefore, it is necessary for T0CKI to be high for at least 2TOSC (and a small RC delay of 20 ns) and low for at least 2TOSC (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple counter-type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4TOSC (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

6.1.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 6-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 6-5: TIMER0 TIMING WITH EXTERNAL CLOCK



Note 1: Delay from clock input change to Timer0 increment is 3Tosc to 7Tosc. (Duration of Q = Tosc). Therefore, the error in measuring the interval between two edges on Timer0 input = ± 4Tosc max.
2: External clock if no prescaler selected, Prescaler output otherwise.
3: The arrows indicate the points in time where sampling occurs.

NOTES:

TABLE 7-3: RESET CONDITIONS FOR SPECIAL REGISTERS

Condition	PCL Addr: 02h	STATUS Addr: 03h
Power-on Reset	1111 1111	1001 1xxx
$\overline{MCLR}$ Reset (normal operation)	1111 1111	u00u uuuu(1)
$\overline{MCLR}$ Wake-up (from SLEEP)	1111 1111	1001 0uuu
WDT Reset (normal operation)	1111 1111	u000 1uuu(2)
WDT Wake-up (from SLEEP)	1111 1111	1000 0uuu
Wake-up from SLEEP on Pin Change	1111 1111	000u uuuu
Brown-out Reset	1111 1111	x00x xxxx

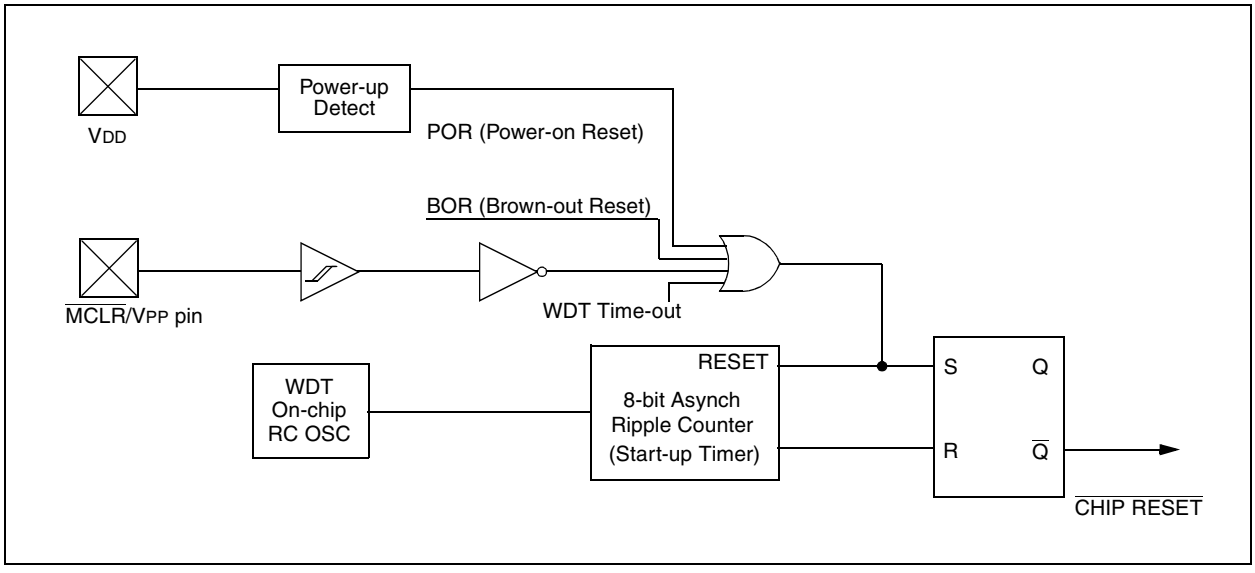
Legend: u = unchanged, x = unknown, - = unimplemented read as '0'.
Note 1: $\overline{TO}$ and $\overline{PD}$ bits retain their last value until one of the other reset conditions occur.
2: The CLRWDT instruction will set the $\overline{TO}$ and $\overline{PD}$ bits.

TABLE 7-4: RESET CONDITIONS FOR ALL REGISTERS

Register	Address	Power-On Reset	$\overline{MCLR}$ or WDT Reset	Wake-up on Pin Change	Brown-out Reset
W	N/A	xxxx xxxx	uuuu uuuu	uuuu uuuu	xxxx xxxx
TRIS	N/A	1111 1111	1111 1111	1111 1111	1111 1111
OPTION	N/A	--11 1111	--11 1111	--11 1111	--11 1111
OPTION2	N/A	--11 1111	--uu uuuu	--uu uuuu	--xx xxxx
INDF	00h	xxxx xxxx	uuuu uuuu	uuuu uuuu	xxxx xxxx
TMR0	01h	xxxx xxxx	uuuu uuuu	uuuu uuuu	xxxx xxxx
PCL(1)	02h	1111 1111	1111 1111	1111 1111	1111 1111
STATUS(1)	03h	1001 1xxx	100? ?uuu	000u uuuu	x00x xxxx
FSR	04h	111x xxxx	111u uuuu	111u uuuu	111x xxxx
PORTA	05h	---- xxxx	---- uuuu	---- uuuu	---- xxxx
PORTB	06h	xxxx xxxx	uuuu uuuu	uuuu uuuu	xxxx xxxx
General Purpose Register Files	07-1Fh	xxxx xxxx	uuuu uuuu	uuuu uuuu	xxxx xxxx

Legend: u = unchanged, x = unknown, - = unimplemented, read as '0', q = see tables in Section 7.10 for possible values.
? = value depends on condition.
Note 1: See Table 7-3 for reset value for specific conditions.

FIGURE 7-6: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



7.4 Power-On Reset (POR)

The PIC16HV540 incorporates on-chip Power-on Reset (POR) circuitry which provides an internal chip reset for most power-up situations. To use this feature, the user merely ties the MCLR/VPP pin to VDD. A simplified block diagram of the on-chip Power-on Reset circuit is shown in Figure 7-7.

The Power-on Reset circuit and the Device Reset Timer (Section 7.5) circuit are closely related. On power-up, the reset latch is set and the DRT is reset. The DRT timer begins counting once it detects MCLR to be high. After the time-out period, which is typically 18 ms, it will reset the reset latch and thus end the on-chip reset signal.

A power-up example where MCLR is not tied to VDD is shown in Figure 7-8. VDD is allowed to rise and stabilize before bringing MCLR high. The chip will actually come out of reset TDRT msec after MCLR goes high.

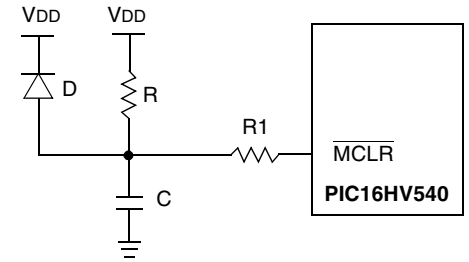
In Figure 7-9, the on-chip Power-on Reset feature is being used (MCLR and VDD are tied together). The VDD is stable before the start-up timer times out and there is no problem in getting a proper reset. However, Figure 7-10 depicts a problem situation where VDD rises too slowly. The time between when the DRT senses a high on the MCLR/VPP pin, and when the MCLR/VPP pin (and VDD) actually reach their full value, is too long. In this situation, when the start-up timer times out, VDD has not reached the VDD (min) value and the chip is, therefore, not guaranteed to function correctly. For such situations, we recommend that external RC circuits be used to achieve longer POR delay times (Figure 7-7).

Note:	When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met.

For more information on PIC16HV540 POR, see *Power-Up Considerations* - AN522 in the Embedded Control Handbook.

The POR circuit does not produce an internal reset when VDD declines.

FIGURE 7-7: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



- External Power-On Reset circuit is required only if VDD power-up is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.
- R < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device electrical specification.
- R1 = 100Ω to 1 kΩ will limit any current flowing into MCLR from external capacitor C in the event of MCLR pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

7.5 Device Reset Timer (DRT)

In the PIC16HV540, the Device Reset Timer (DRT) runs any time the device is powered up. DRT runs from reset and varies based on oscillator selection (see Table 7-5).

The DRT provides a fixed 18 ms nominal time-out on reset. The DRT operates on an internal RC oscillator. The processor is kept in RESET as long as the DRT is active. The DRT delay allows Vdd to rise above Vdd min., and for the oscillator to stabilize.

Oscillator circuits based on crystals or ceramic resonators require a certain time after power-up to establish a stable oscillation. The on-chip DRT keeps the device in a RESET condition for approximately 18 ms after the voltage on the $\overline{MCLR}$/VPP pin has reach a logic high (VIH) level. Thus, external RC networks connected to the $\overline{MCLR}$ input are not required in most cases, allowing for savings in cost-sensitive and/or space restricted applications.

The Device Reset time delay will vary from chip to chip due to VDD, temperature, and process variation. See AC parameters for details.

The DRT will also be triggered upon a Watchdog Timer time-out, $\overline{MCLR}$ Reset, Wake-up from SLEEP on Pin Change and Brown-out Reset. When the external RC oscillator mode is selected, all DRT periods, after the initial POR, are 1 ms (typical).

TABLE 7-5: DRT (DEVICE RESET TIMER PERIOD)

Oscillator Configuration	POR Reset	Subsequent Resets
EXTRC	18 ms (typical)	1 ms (typical)
LP, XT & HS	18 ms (typical)	18 ms (typical)

7.6 Brown-Out Detect (BOD)

The PIC16HV540 has on-chip Brown-out Detect circuitry. If enabled and if the internal power, V_{REG}, falls below parameter B_{VDD} (See Section 10.1), for greater time than parameter T_{BOD} (See Table 10-3) the brown-out condition will reset the chip. A reset is not guaranteed if V_{REG} falls below B_{VDD} for less time than parameter (T_{BOD}).

On resets (Brown-out, Watchdog, $\overline{MCLR}$ and Wake-up on Pin Change), the chip will remain in reset until V_{REG} rises above B_{VDD}. Once the B_{VDD} threshold has been met the DRT will now be invoked and will keep the chip in reset an additional 18mS (LP, XT and HS oscillator modes) or 1mS for EXTRC.

If V_{REG} drops below B_{VDD} while the DRT is running, the chip will go back into a Brown-out Reset and the DRT will be re-initialized. Once V_{REG} rises above the B_{VDD}, the DRT will execute the specified time period. Figure 7-11 shows typical Brown-out situations.

The Brown-out Detect circuit can be disabled or enabled by setting the $\overline{BODEN}$ bit in the OPTION2 SFR. The Brown-out Detect is disabled upon all Power-on Resets (POR).

7.6.1 IMPLEMENTING THE ON-CHIP BOD CIRCUIT

The PIC16HV540 BOD circuitry differs from “conventional” brown-out detect circuitry in that the BOD circuitry on the PIC16HV540 does not directly detect “dips” in the external V_{DD} supply voltage but rather the internal V_{REG}. The functionality of the BOD circuitry ensures that program execution will halt and a reset state will be entered into prior to the internal logic becoming corrupted. The BOD circuit has two selectable voltage settings, nominally 5V and 3V. Each regulation voltage setting with its associated minimum and maximum B_{VDD} parameters has an intended operational mode that must be carefully considered.

For the 5V V_{REG} setting, the minimum B_{VDD} parameter is 2.7V. This minimum B_{VDD} voltage is below the part V_{DD} minimum requirements. This operational setting is primarily intended for use when the PIC16HV540 is operating at 4Mhz and V_{DD} > 5.5V.

For the 3V V_{REG} setting, the minimum B_{VDD} parameter is 1.8V. This minimum B_{VDD} voltage is below the part V_{DD} minimum requirements. This operational setting is primarily intended for use when the PIC16HV540 is in SLEEP. RAM retention is protected by the 1.8V trip level.

For the regulation and Brown-out circuits to function as intended the applied V_{DD} is nominally 0.5V greater than the regulation voltage setting.

Finally, if the internal brown-out circuit is deemed not to meet system design requirements then an external brown-out protection circuit may be required. Microchip offers a complete family of voltage supervisor products which can meet most design requirements.

8.0 INSTRUCTION SET SUMMARY

Each PIC16HV540 instruction is a 12-bit word divided into an OPCODE, which specifies the instruction type, and one or more operands which further specify the operation of the instruction. The PIC16HV540 instruction set summary in Table 8-2 groups the instructions into byte-oriented, bit-oriented, and literal and control operations. Table 8-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator is used to specify which one of the 32 file registers is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an 8 or 9-bit constant or literal value.

TABLE 8-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0 (store result in W) d = 1 (store result in file register 'f') Default is d = 1
label	Label name
TOS	Top of Stack
PC	Program Counter
WDT	Watchdog Timer Counter
TO	Time-Out bit
PD	Power-Down bit
dest	Destination, either the W register or the specified register file location
[ ]	Options
( )	Contents
→	Assigned to
< >	Register bit field
∈	In the set of
italics	User defined term (font is courier)

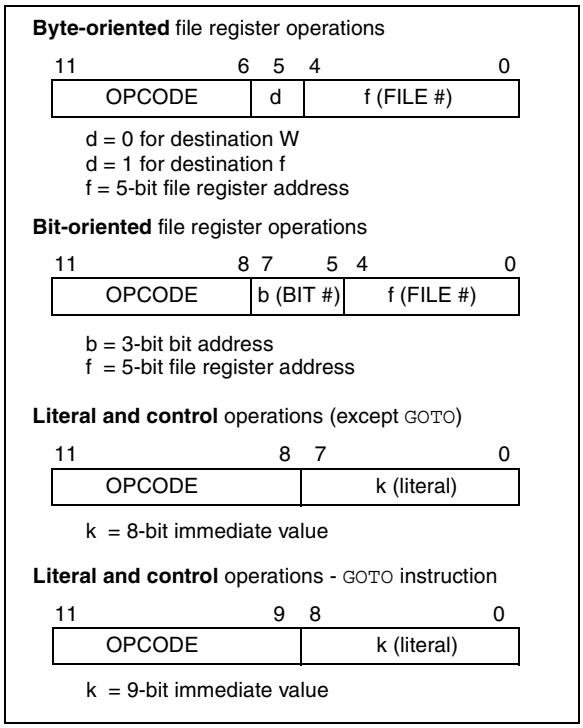
All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 μs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2 μs.

Figure 8-1 shows the three general formats that the instructions can have. All examples in the figure use the following format to represent a hexadecimal number:

0xhhh

where 'h' signifies a hexadecimal digit.

FIGURE 8-1: GENERAL FORMAT FOR INSTRUCTIONS



BSF **Bit Set f**

Syntax: [*label*] BSF f,b

Operands: 0 ≤ f ≤ 31
0 ≤ b ≤ 7

Operation: 1 → (f<b>)

Status Affected: None

Encoding:

0101	bbbf	ffff

Description: Bit 'b' in register 'f' is set.

Words: 1

Cycles: 1

Example:
```
BSF     FLAG_REG,   7
```
Before Instruction
FLAG_REG = 0x0A
After Instruction
FLAG_REG = 0x8A

BTFSC **Bit Test f, Skip if Clear**

Syntax: [*label*] BTFSC f,b

Operands: 0 ≤ f ≤ 31
0 ≤ b ≤ 7

Operation: skip if (f<b>) = 0

Status Affected: None

Encoding:

0110	bbbf	ffff

Description: If bit 'b' in register 'f' is 0 then the next instruction is skipped.
If bit 'b' is 0 then the next instruction fetched during the current instruction execution is discarded, and an NOP is executed instead, making this a 2 cycle instruction.

Words: 1

Cycles: 1(2)

Example:
```
HERE    BTFSC   FLAG,1
FALSE   GOTO    PROCESS_CODE
TRUE    •
        •
        •
```
Before Instruction
PC = address (HERE)
After Instruction
if FLAG<1> = 0,
PC = address (TRUE);
if FLAG<1> = 1,
PC = address (FALSE)

BTFSS **Bit Test f, Skip if Set**

Syntax: [*label*] BTFSS f,b

Operands: 0 ≤ f ≤ 31
0 ≤ b < 7

Operation: skip if (f<b>) = 1

Status Affected: None

Encoding:

0111	bbbf	ffff

Description: If bit 'b' in register 'f' is '1' then the next instruction is skipped.
If bit 'b' is '1', then the next instruction fetched during the current instruction execution, is discarded and an NOP is executed instead, making this a 2 cycle instruction.

Words: 1

Cycles: 1(2)

Example:
```
HERE    BTFSS   FLAG,1
FALSE   GOTO    PROCESS_CODE
TRUE    •
        •
        •
```
Before Instruction
PC = address (HERE)
After Instruction
If FLAG<1> = 0,
PC = address (FALSE);
if FLAG<1> = 1,
PC = address (TRUE)

MOVF **Move f**

Syntax: [*label*] MOVF f,d

Operands: $0 \le f \le 31$
$d \in [0,1]$

Operation: (f) → (dest)

Status Affected: Z

Encoding:

0010	00df	ffff

Description: The contents of register 'f' is moved to destination 'd'. If 'd' is 0, destination is the W register. If 'd' is 1, the destination is file register 'f'. 'd' is 1 is useful to test a file register since status flag Z is affected.

Words: 1

Cycles: 1

Example:
```
MOVF    FSR,    0
```
After Instruction
W = value in FSR register

MOVLW **Move Literal to W**

Syntax: [*label*] MOVLW k

Operands: $0 \le k \le 255$

Operation: k → (W)

Status Affected: None

Encoding:

1100	kkkk	kkkk

Description: The eight bit literal 'k' is loaded into the W register. The don't cares will assemble as 0s.

Words: 1

Cycles: 1

Example:
```
MOVLW   0x5A
```
After Instruction
W = 0x5A

MOVWF **Move W to f**

Syntax: [*label*] MOVWF f

Operands: $0 \le f \le 31$

Operation: (W) → (f)

Status Affected: None

Encoding:

0000	001f	ffff

Description: Move data from the W register to register 'f'.

Words: 1

Cycles: 1

Example:
```
MOVWF   TEMP_REG
```
Before Instruction
TEMP_REG = 0xFF
W = 0x4F

After Instruction
TEMP_REG = 0x4F
W = 0x4F

NOP **No Operation**

Syntax: [*label*] NOP

Operands: None

Operation: No operation

Status Affected: None

Encoding:

0000	0000	0000

Description: No operation.

Words: 1

Cycles: 1

Example:
```
NOP
```


OPTION **Load OPTION Register**

Syntax: [*label*] OPTION

Operands: None

Operation: (W) → OPTION

Status Affected: None

Encoding:

0000	0000	0010

Description: The content of the W register is loaded into the OPTION register.

Words: 1

Cycles: 1

Example

```
OPTIO
  N
```

Before Instruction
W = 0x07

After Instruction
OPTION = 0x07

RETLW **Return with Literal in W**

Syntax: [*label*] RETLW k

Operands: 0 ≤ k ≤ 255

Operation: k → (W);
TOS → PC

Status Affected: None

Encoding:

1000	kkkk	kkkk

Description: The W register is loaded with the eight bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two cycle instruction.

Words: 1

Cycles: 2

Example:

```
CALL TABLE ;W contains
           ;table offset
           ;value.
•          ;W now has table
•          ;value.
•
TABLE      ADDWF PC   ;W = offset
           RETLW k1   ;Begin table
           RETLW k2   ;
           •
           •
           •
           RETLW kn   ; End of table
```

Before Instruction
W = 0x07

After Instruction
W = value of k8

RLF **Rotate Left f through Carry**

Syntax: [*label*] RLF f,d

Operands: 0 ≤ f ≤ 31
d ∈ [0,1]

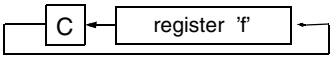
Operation: See description below

Status Affected: C

Encoding:

0011	01df	ffff

Description: The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is stored back in register 'f'.



Words: 1

Cycles: 1

Example:

```
RLF     REG1,0
```

Before Instruction
REG1 = 1110 0110
C = 0

After Instruction
REG1 = 1110 0110
W = 1100 1100
C = 1

RRF **Rotate Right f through Carry**

Syntax: [*label*] RRF f,d

Operands: 0 ≤ f ≤ 31
d ∈ [0,1]

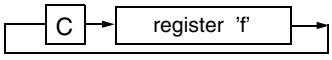
Operation: See description below

Status Affected: C

Encoding:

0011	00df	ffff

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.



Words: 1

Cycles: 1

Example:

```
RRF     REG1,0
```

Before Instruction
REG1 = 1110 0110
C = 0

After Instruction
REG1 = 1110 0110
W = 0111 0011
C = 0

NOTES:

11.0 DC AND AC CHARACTERISTICS - PIC16HV540

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed. In some graphs or tables the data presented are outside specified operating range (e.g., outside specified VDD range). This is for information only and devices will operate properly only within the specified range.

The data presented in this section is a statistical summary of data collected on units from different lots over a period of time. "Typical" represents the mean of the distribution while "max" or "min" represents (mean + 3σ) and (mean – 3σ) respectively, where σ is standard deviation.

FIGURE 11-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

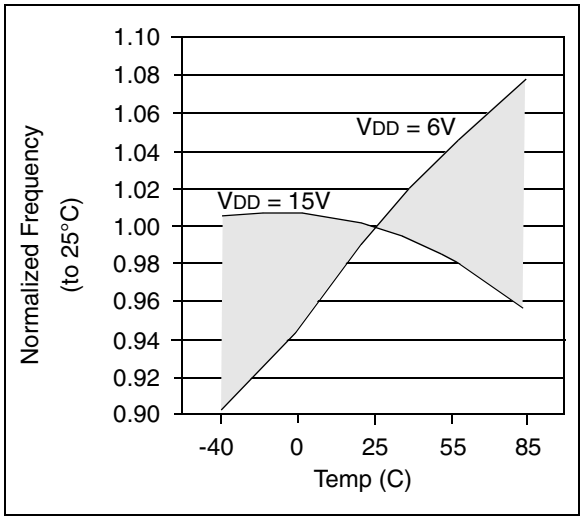


TABLE 11-1: RC OSCILLATOR FREQUENCIES

CEXT	REXT	Average FOSC, VIO = 5V	
		25°C, VDD = 6V	25°C, VDD = 15V
20 pF	3.3k	4986.7 kHz	**(1)**
	5k	4233.3 kHz	**(1)**
	10k	2656.7 kHz	5150.0 kHz
	24k	1223.3 kHz	3286.7 kHz
	100k	325.7 kHz	955.7 kHz
	390k	79.0 kHz	250.7 kHz
100 pF	3.3k	1916.7 kHz	**(1)**
	5k	1593.3 kHz	**(1)**
	10k	995.7 kHz	2086.7 kHz
	24k	448.3 kHz	1210.0 kHz
	100k	116.0 kHz	355.7 kHz
	390k	28.3 kHz	89.7 kHz
300 pF	3.3k	744 kHz	**(1)**
	5k	620.3 kHz	**(1)**
	10k	382.0 kHz	817.3 kHz
	24k	169.7 kHz	483.0 kHz
	100k	44.1 kHz	135.7 kHz
	390k	10.6 kHz	34.4 kHz

Note 1: This combination of R, C and VDD draws too much current and prohibits oscillator operation.

FIGURE 11-2: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD (CEXT = 20pF)

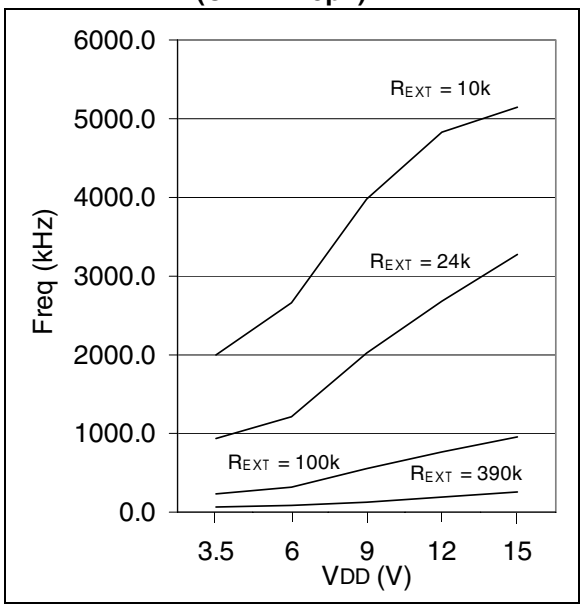
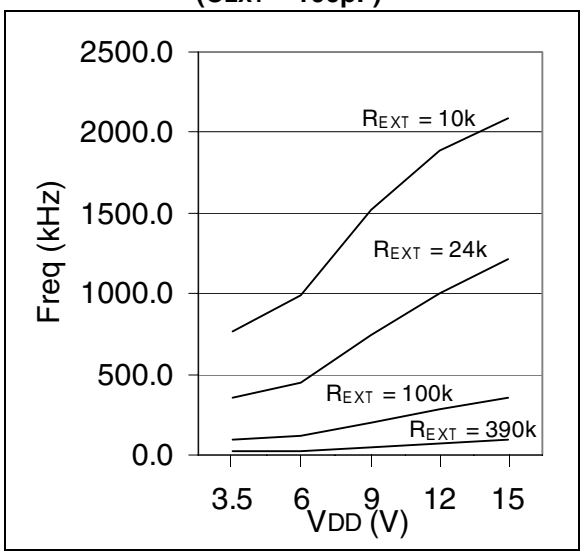
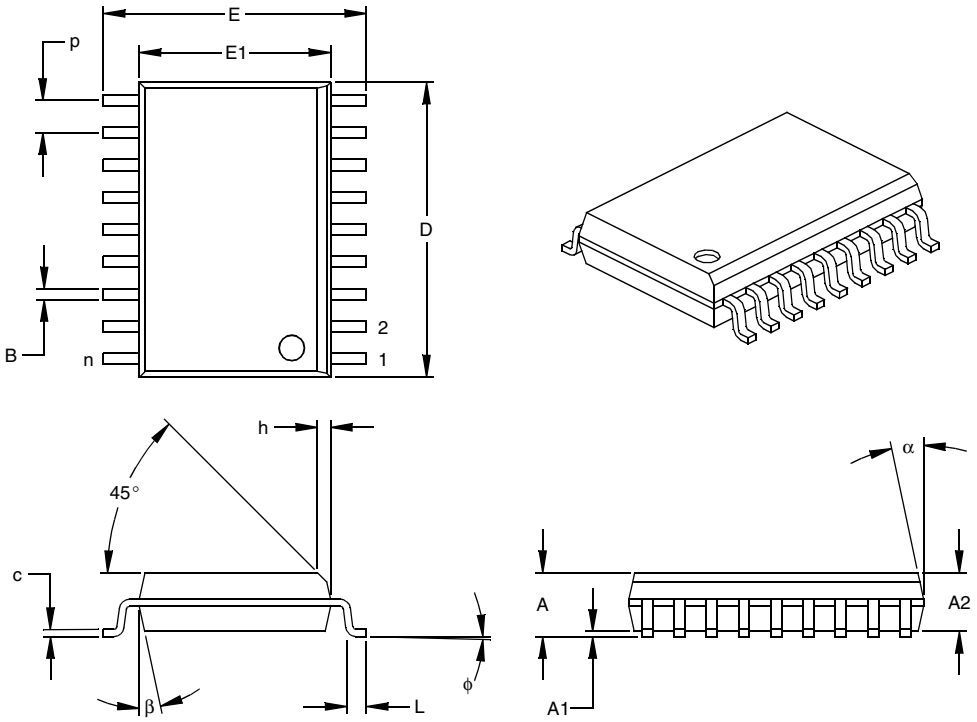


FIGURE 11-3: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD (CEXT = 100pF)



12.2 18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

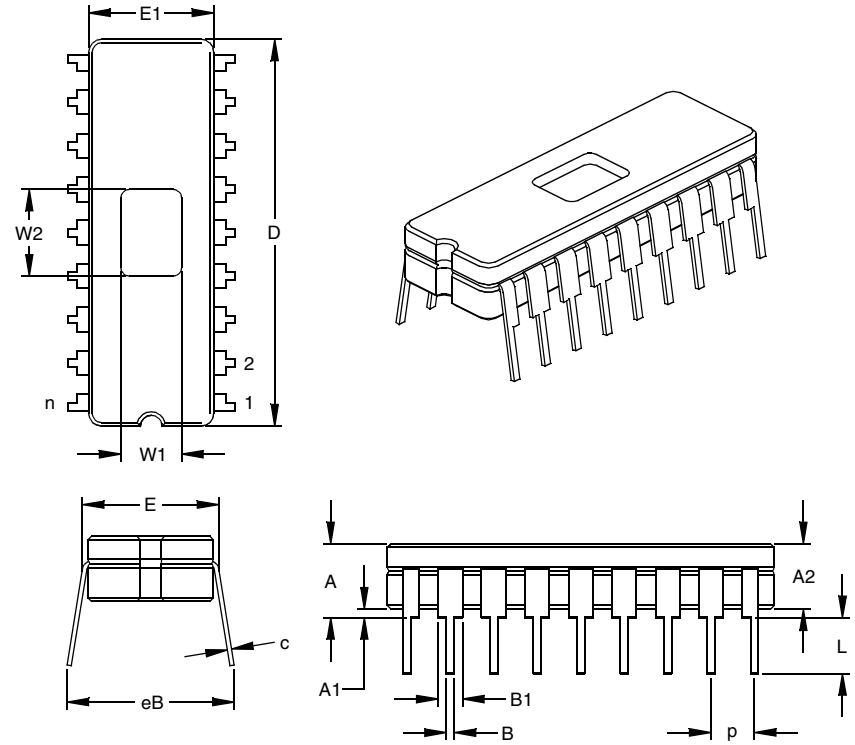


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	ϕ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-051

12.3 18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing §	eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

* Controlling Parameter
§ Significant Characteristic
JEDEC Equivalent: MO-036
Drawing No. C04-010

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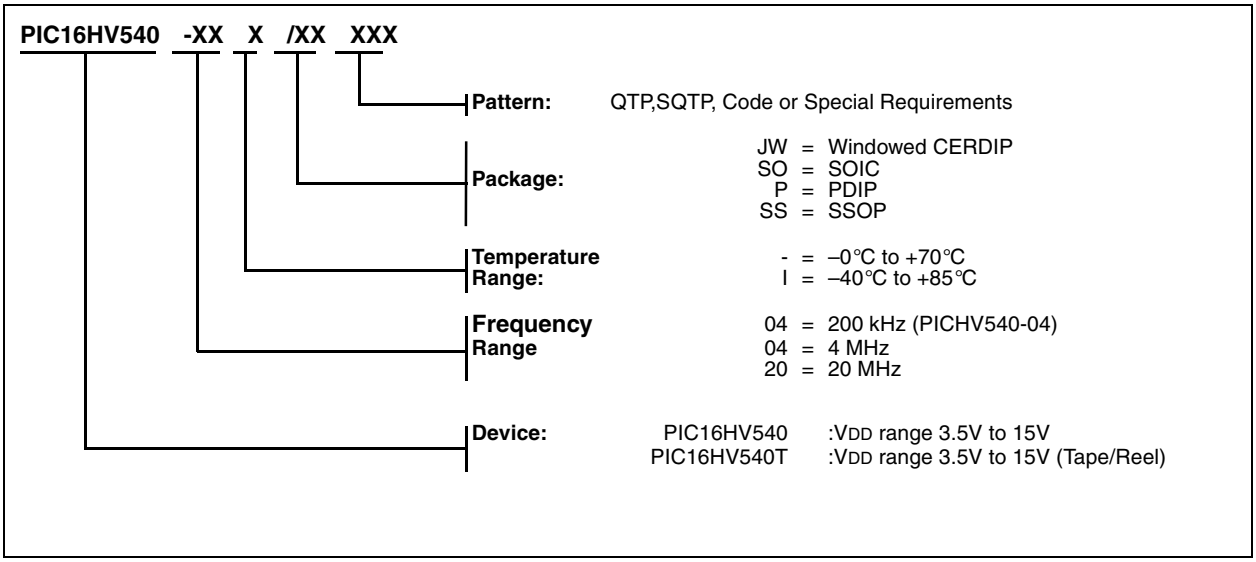
PIC16HV540 PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Sales and Support

Data Sheets
Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Corporate Literature Center U.S. FAX: (480) 786-7277.
3. The Microchip Worldwide Site (www.microchip.com)

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